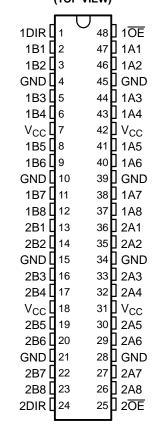
# SN54ABT16245A, SN74ABT16245A 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS300G-MARCH 1994-REVISED JANUARY 2006

#### **FEATURES**

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Typical  $V_{OLP}$  (Output Ground Bounce) <1 V at  $V_{CC}$  = 5 V,  $T_A$  = 25°C
- High-Impedance State During Power Up and Power Down
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (–32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Latch-Up Performance Exceeds 500 mA Per JESD 70
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Includes Plastic Thin Very Small-Outline (DGV), Shrink Small-Outline (DL), and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic (WD) Flat Package Using 25-mil Center-to-Center Spacings

SN54ABT16245A... WD PACKAGE SN74ABT16245A... DGG, DGV, OR DL PACKAGE (TOP VIEW)



#### **DESCRIPTION**

The 'ABT16245A devices are 16-bit noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceviers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses are effectively isolated.

When  $V_{CC}$  is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impendance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16245A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT16245A is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

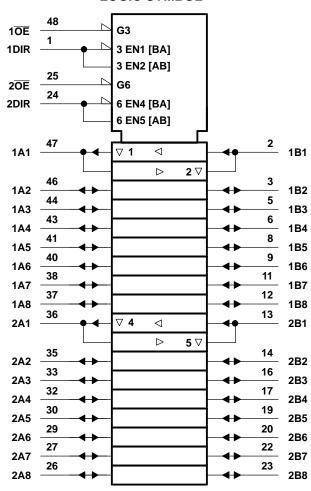
Widebus, EPIC-IIB are trademarks of Texas Instruments.



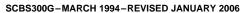
# FUNCTION TABLE (EACH 8-BIT SECTION)

INP	UTS	OPERATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation

# LOGIC SYMBOL(1)

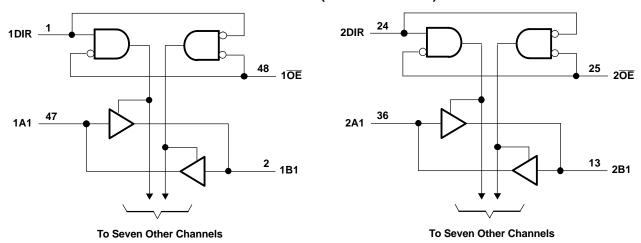


(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.





### **LOGIC DIAGRAM (POSITIVE LOGIC)**



# Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

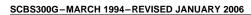
			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	7	٧
VI	Input voltage range (except I/O ports)(2)		-0.5	7	V
Vo	Voltage range applied to any output in the high o	-0.5	5.5	V	
	Current into any output in the law state	SN54ABT16245A		96	A
IO	Current into any output in the low state	SN74ABT16245A		128	mA
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-18	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
		DGG package		89	
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	DGV package		93	°C/W
		DL package		94	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>(2)</sup> The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>(3)</sup> The package thermal impedance is calculated in accordance with JESD 51.

# SN54ABT16245A, SN74ABT16245A 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS





# Recommended Operating Conditions<sup>(1)</sup>

			SN54ABT	16245A	SN74ABT	16245A	UNIT
			MIN	MAX	MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		4.5	5.5	4.5	5.5	V
V <sub>IH</sub>	High-level input voltage	2		2		V	
$V_{IL}$	Low-level input voltage		0.8		0.8	V	
VI	Input voltage	0	$V_{CC}$	0	$V_{CC}$	V	
I <sub>OH</sub>	High-level output current			-24		-32	mA
I <sub>OL</sub>	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		200		μs/V	
T <sub>A</sub>	Operating free-air temperature		-55	125	-40	85	°C

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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#### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

DAD	METED	TEST CO	NUDITIONS	Т	Γ <sub>A</sub> = 25°0	3	SN54ABT	16245A	SN74ABT1	6245A	LINUT
PARA	AMETER	IESI CC	ONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	MIN	MAX	MIN	MAX	UNIT
$V_{IK}$		$V_{CC} = 4.5 \text{ V},$	$I_I = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
V		V <sub>CC</sub> = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
$V_{OH}$		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2				V
		V <sub>CC</sub> = 4.5 V	$I_{OH} = -32 \text{ mA}$	2(2)					2		
\ <u>'</u>		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.55		0.55			V
$V_{OL}$		V <sub>CC</sub> = 4.5 V	$I_{OL} = 64 \text{ mA}$			0.55(2)				0.55	V
$V_{\text{hys}}$					100						mV
	Control inputs	$V_{CC} = 0 \text{ to } 5.5 \text{ V}, V_{I} = V_{CC}$	$V_{CC} = 0$ to 5.5 V, $V_I = V_{CC}$ or GND			±1		±1		±1	μA
l <sub>l</sub>	A or B port	V <sub>CC</sub> = 2.1 V to 5.5 V, V	I = V <sub>CC</sub> or GND			±20 <sup>(2)</sup>		±100		±20	μΑ
l <sub>OZPU</sub>		$V_{CC} = 0 \text{ to } 2.1 \text{ V, } V_{O} =$	0.5 V to 2.7 V, <del>OE</del> = X			±50(3)		±50 <sup>(3)</sup>		±50	μΑ
I <sub>OZPD</sub>		$V_{CC} = 2.1 \text{ V to } 0, V_{O} =$	0.5 V to 2.7 V, <del>OE</del> = X			±50 <sup>(3)</sup>		±50 <sup>(3)</sup>		±50	μΑ
I <sub>OZH</sub> <sup>(4)</sup>		$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V, V}$			10 <sup>(5)</sup>		10		10 <sup>(5)</sup>	μΑ	
I <sub>OZL</sub> <sup>(4)</sup>		$V_{CC}$ = 2.1 V to 5.5 V, $V_{O}$ = 0.5 V, OE $\geq$ 2 V				-10 <sup>(5)</sup>		-10		-10 <sup>(5)</sup>	μΑ
I <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 5.5 \text{ V}$			±100				±100	μΑ
I <sub>CEX</sub>		V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μА
I <sub>O</sub> <sup>(6)</sup>		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
			Outputs high			2		2		2	
$I_{CC}$	A or B port	$V_{CC} = 5.5 \text{ V}, I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low			32		32		32	mA
	<b>P</b> 511	1 100 1111	Outputs disabled			2		2		2	
		$V_{CC} = 5.5 \text{ V},$	Outputs enabled			2		1.5		2	
$\Delta I_{CC}^{(7)}$	Data inputs	One inputs at 3.4 V, Other inputs at V <sub>CC</sub> or GND	Outputs disabled			0.05		1		0.05	mA
	Control inputs	$V_{CC}$ = 5.5 V, One input at 3.4 V, Other inputs at $V_{CC}$ or GND				1.5		1.5		1.5	
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			3						pF
C <sub>o</sub>	A or B port	V <sub>O</sub> = 2.5 V or 0.5 V			6						pF

- All typical values are at  $V_{CC}$  = 5 V. On products compliant to MIL-PRF-38535, this parameter does not apply. On products compliant to MIL-PRF-38535, this parameter is not production tested.
- The parameters  $I_{\text{OZH}}$  and  $I_{\text{OZL}}$  include the input leakage current.
- This limit may vary among suppliers.
- (6) Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V<sub>CC</sub> or GND.

# SN54ABT16245A, SN74ABT16245A 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS300G-MARCH 1994-REVISED JANUARY 2006



# **Switching Characteristics**

over recommended operating ranges of supply voltage and operating free-air temperature,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

			SN54ABT16245A						
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>0</sub>	<sub>CC</sub> = 5 V <sub>A</sub> = 25°C	,	MIN	MAX	UNIT	
			MIN	TYP	MAX				
t <sub>PLH</sub>	A or B	B or A	0.5	2.2	3.4	0.5	4	ns	
t <sub>PHL</sub>	AOIB		0.5	2.3	3.8	0.5	4.6		
t <sub>PZH</sub>	<del>OE</del>	B or A	8.0	3.6	5.2	0.8	5.5	ne	
t <sub>PZL</sub>	OL	BUIA	0.9	3.7	6.1	0.1	7.3	ns	
t <sub>PHZ</sub>	<del>OE</del>	B or A	1.3	4.4	5.8	1.3	6.3	ne	
t <sub>PLZ</sub>	OL	BUIA	1.4	3.3	4.7	1.4	5.5	ns	

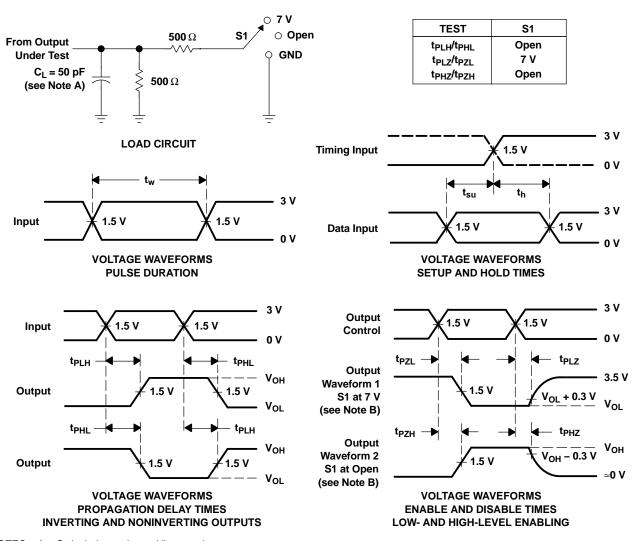
# **Switching Characteristics**

over recommended operating ranges of supply voltage and operating free-air temperature,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		<sub>CC</sub> = 5 V <sub>A</sub> = 25°C		MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	A or B	B or A	1	2.2	3.4	1	3.9	2
t <sub>PHL</sub>	AUID	BULA	1	2.3	3.7	1	4.2	ns
t <sub>PZH</sub>	<del>OE</del>	B or A	1	3.6	5.2	1	6.3	20
t <sub>PZL</sub>	OL	BULK	1	3.7	5.4	1	6.4	ns
t <sub>PHZ</sub>	OE B or A		2	4.4	5.8	2	6.3	ns
t <sub>PLZ</sub>	OL	BULA	1.5	3.3	4.7	1.5	5.2	115



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
1O16245ADLRG4	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16245A
1O16245ADLRG4.B	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16245A
5962-9317501MXA	Active	Production	CFP (WD)   48	15   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9317501MX A SNJ54ABT16245A WD
74ABT16245ADGGRG4	Active	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16245A
74ABT16245ADGVRG4	Active	Production	TVSOP (DGV)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AH245A
74ABT16245ADGVRG4.B	Active	Production	TVSOP (DGV)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AH245A
SN74ABT16245ADGGR	Active	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16245A
SN74ABT16245ADGGR.B	Active	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16245A
SN74ABT16245ADGVR	Active	Production	TVSOP (DGV)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AH245A
SN74ABT16245ADGVR.B	Active	Production	TVSOP (DGV)   48	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AH245A
SN74ABT16245ADL	Active	Production	SSOP (DL)   48	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16245A
SN74ABT16245ADL.B	Active	Production	SSOP (DL)   48	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16245A
SN74ABT16245ADLR	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16245A
SN74ABT16245ADLR.B	Active	Production	SSOP (DL)   48	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16245A
SNJ54ABT16245AWD	Active	Production	CFP (WD)   48	15   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9317501MX A SNJ54ABT16245A WD

 $<sup>^{\</sup>mbox{(1)}}$  Status: For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

# PACKAGE OPTION ADDENDUM

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(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54ABT16245A, SN74ABT16245A:

Catalog: SN74ABT16245A

Enhanced Product: SN74ABT16245A-EP, SN74ABT16245A-EP

Military: SN54ABT16245A

NOTE: Qualified Version Definitions:

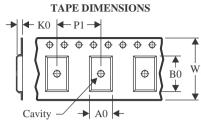
- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

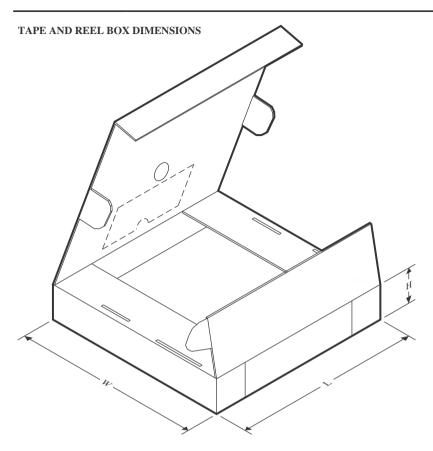


#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
1O16245ADLRG4	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
74ABT16245ADGVRG4	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74ABT16245ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABT16245ADGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74ABT16245ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1



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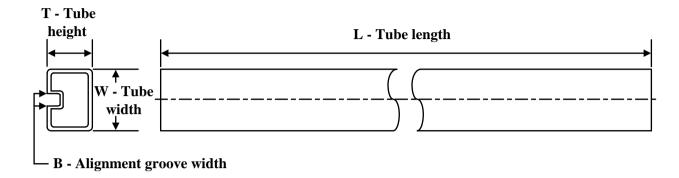
#### \*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
1O16245ADLRG4	SSOP	DL	48	1000	356.0	356.0	53.0
74ABT16245ADGVRG4	TVSOP	DGV	48	2000	353.0	353.0	32.0
SN74ABT16245ADGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74ABT16245ADGVR	TVSOP	DGV	48	2000	353.0	353.0	32.0
SN74ABT16245ADLR	SSOP	DL	48	1000	356.0	356.0	53.0

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT16245ADL	DL	SSOP	48	25	473.7	14.24	5110	7.87
SN74ABT16245ADL.B	DL	SSOP	48	25	473.7	14.24	5110	7.87

# DGV (R-PDSO-G\*\*)

### 24 PINS SHOWN

#### PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

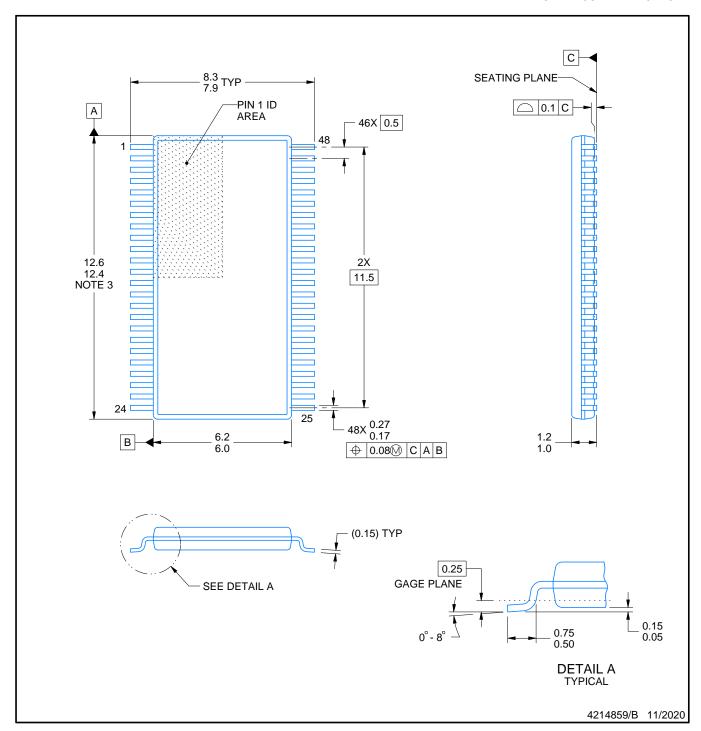
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



SMALL OUTLINE PACKAGE



### NOTES:

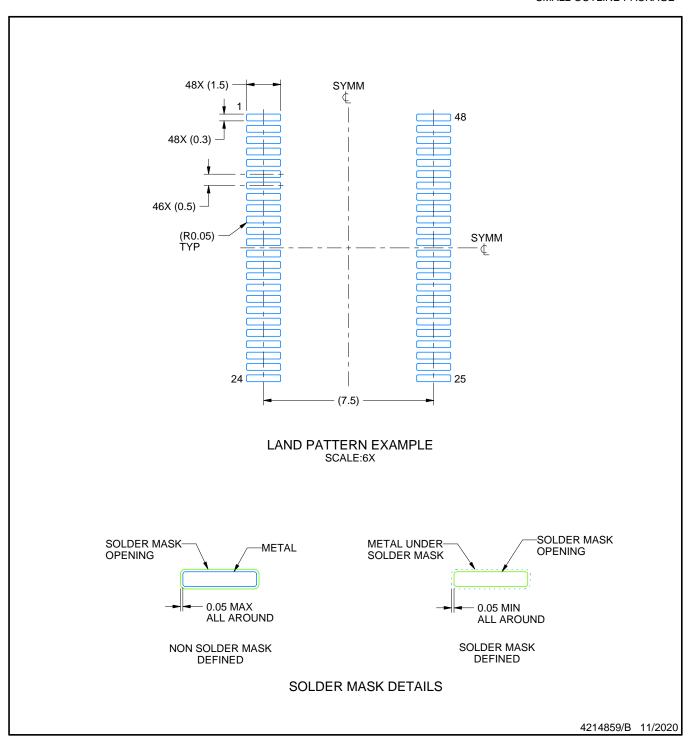
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

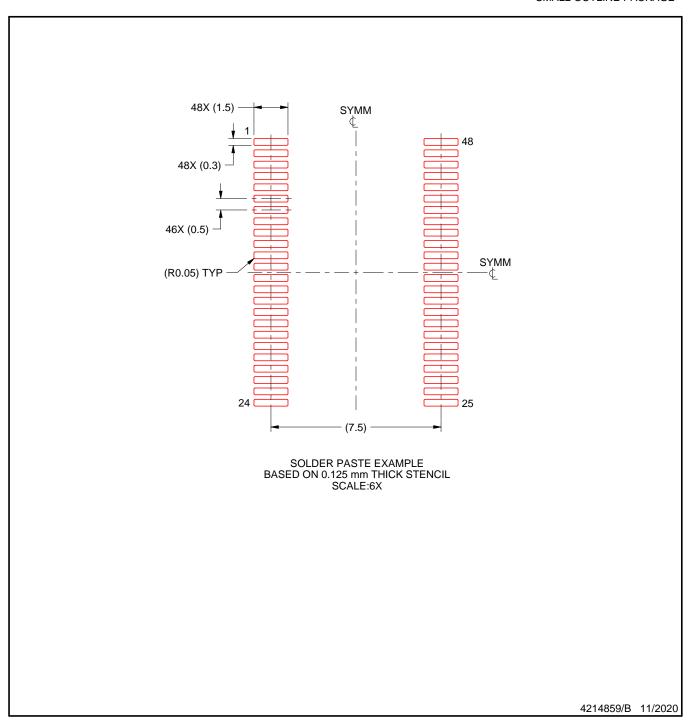


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



# DGG (R-PDSO-G\*\*)

# PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

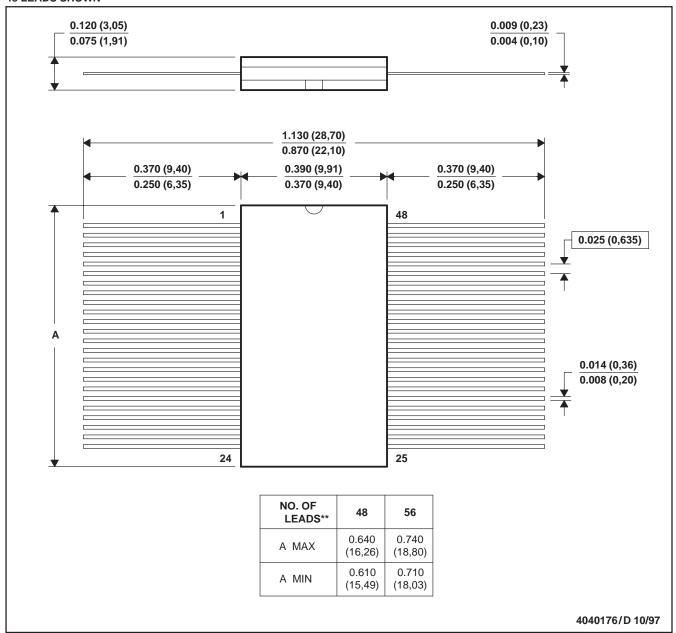
C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

### WD (R-GDFP-F\*\*)

#### **CERAMIC DUAL FLATPACK**

#### **48 LEADS SHOWN**



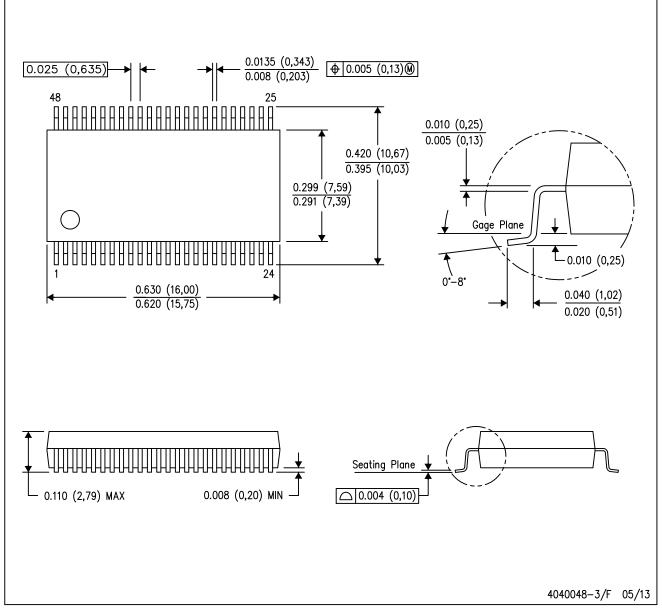
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

# DL (R-PDSO-G48)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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